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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10066645	FILING DATE 02/06/2002	CLASS 438	SUBCLASS 630	GAH 2841	EXAMINER NEMA PEREZ NY
**APPLICANTS: Kellar Scot; Kim Sarah; List R.;					
**CONTINUING DATA VERIFIED:					
<h1>BEST AVAILABLE COPY</h1>					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		219.40606X00			
Verified and Acknowledged Examiners's initials					
TITLE : Dielectric recess for wafer-to-wafer and die-to-die metal bonding and method of fabricating the same.					
<small>U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE Amount Due Date Paid		Assistant Examiner	
		Primary Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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